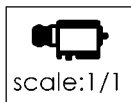
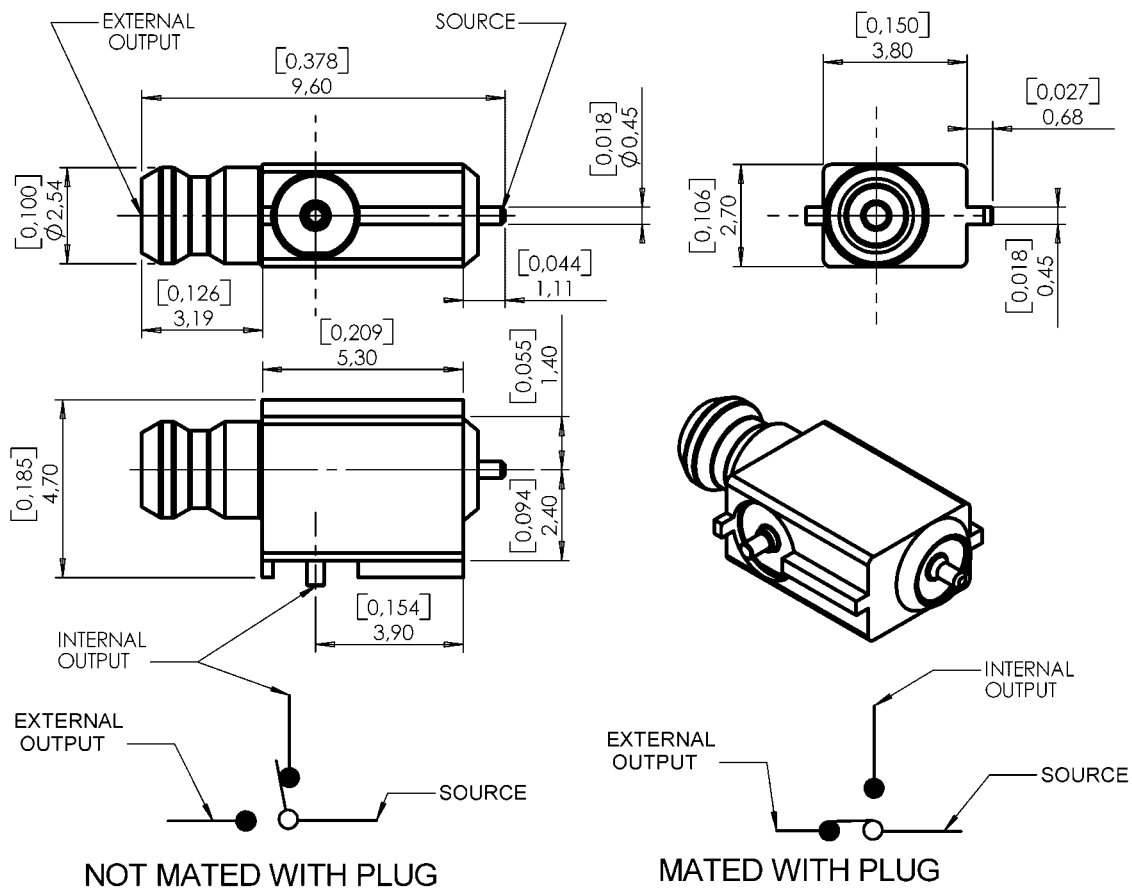


EDGE CARD SWITCH
PACKAGING BY REEL OF 100

R199.006.813

Series : MOEBIUS



All dimensions are in mm/[inch]



COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR
CENTER CONTACT	BRASS	NPGR
OUTER CONTACT	BRASS	NPGR
INSULATOR	-PEEK	
GASKET	-	
OTHERS PARTS	-NC	
.	.	.
.	.	.

Issue : 0717 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



EDGE CARD SWITCH
PACKAGING BY REEL OF 100

R199.006.813

Series : MOEBIUS

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance **50** Ω
 Frequency **0-6** GHz
 VSWR (not mated) **1.2+0.05** x F(GHz) Maxi
 VSWR (mated with plug) **1.05+0.05** x F(GHz) Maxi

Operating temperature **-40/+110** ° C
 Hermetic seal Atm.cm3/s
 Panel leakage

*Insertion loss DC to 2 Ghz **0.15** dB Maxi
 *Insertion loss 2 to 3 Ghz **0.2** dB Maxi
 *Insertion loss 3 to 6 Ghz **0.5** dB Maxi
 * not mated with PCB

OTHER CHARACTERISTICS

Isolation loss DC to 1Ghz **30 dB min
 Isolation loss 1 to 3Ghz **20 dB min
 Isolation loss 3 to 6Ghz **20 dB min
 ** mated with plug

Voltage rating **100** Veff Maxi
 Dielectric withstanding voltage **250** Veff mini
 Insulation resistance **3000** MΩ mini

Assembly instruction

Others :
 Vibration no electrical discontinuity of 10 μs or more
 Condition test : 10 to 500 Hz , single amplitude of 1.5 mm , speed of 10 g , 2 hours in each of the 3 axis

MECHANICAL CHARACTERISTICS

Mating life **25000** Cycles
 Weight **0,37000.** g

Issue : 0717 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



EDGE CARD SWITCH
PACKAGING BY REEL OF 100

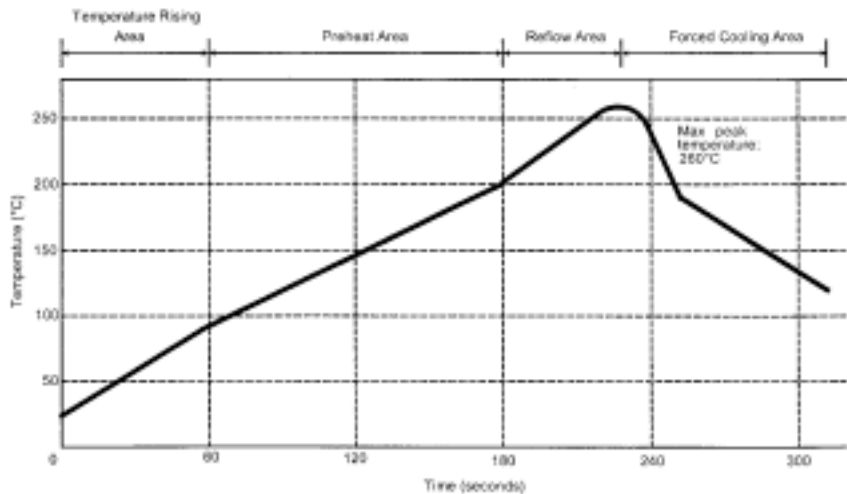
R199.006.813

Series : MOEBIUS

SOLDER PROCEDURE

1. Deposition of solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
 We advise a thickness of 150 microns mini (0.006 inch mini). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.
 Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
 Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0717 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

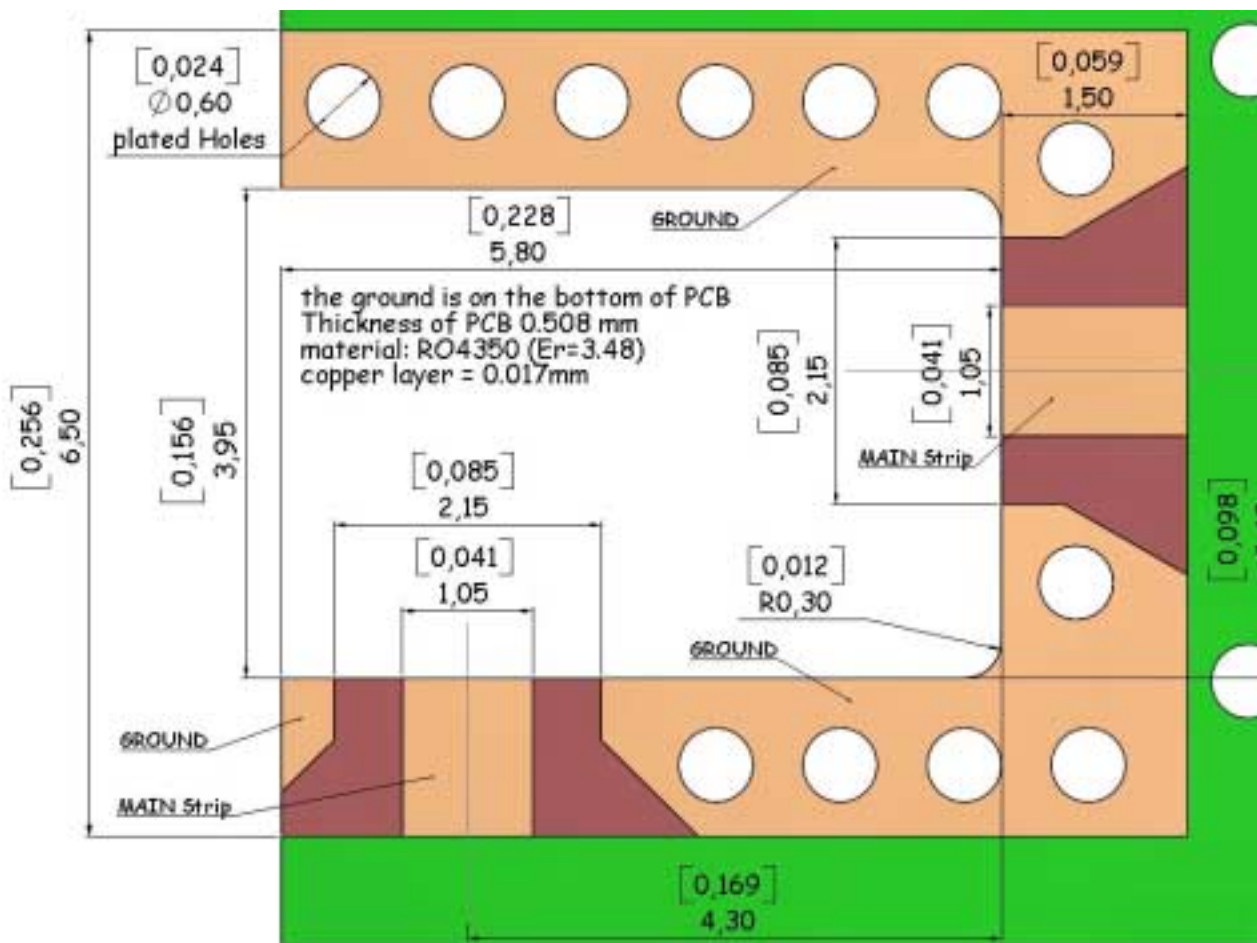


EDGE CARD SWITCH
PACKAGING BY REEL OF 100

R199.006.813

Series : MOEBIUS

INFORMATION ABOUT PAD



Issue : 0717 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

